

## **60V N-Channel Enhancement Mode Power MOSFET**

# **Description**

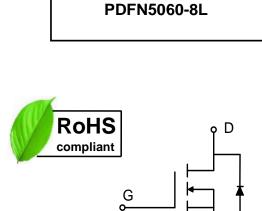
WMB75N06T1 uses advanced power trench technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

## **Features**

- $V_{DS}$ = 60 V,  $I_{D}$  = 75 A  $R_{DS(on)}$  < 8.5m $\Omega$  @  $V_{GS}$  = 10 V  $R_{DS(on)}$  < 12m $\Omega$  @  $V_{GS}$  = 4.5V
- Low R<sub>DS(on)</sub>
- Low Gate Charge
- 100% EAS Guaranteed

# **Applications**

- Power Management Switches
- Synchronous Rectification for AC/DC Quick Charger



# **Absolute Maximum Ratings**

Parameter		Symbol	Value	Unit
Drain-Source Voltage		V <sub>DS</sub>	60	V
Gate-Source Voltage		V <sub>G</sub> s	±20	V
Continuous Drain Current <sup>1</sup>	T <sub>C</sub> =25°C	- I <sub>D</sub>	75	- A
	T <sub>C</sub> =100°C		47	
Pulsed Drain Current <sup>2</sup>		Іом	280	А
Single Pulse Avalanche Energy <sup>3</sup>		EAS	80	mJ
Avalanche Current		las	40	Α
Total Power Dissipation <sup>4</sup> T <sub>C</sub> =25°C		P <sub>D</sub>	51.5	W
Operating Junction and Storage Temperature Range		TJ, TSTG	-55 to 150	°C

## **Thermal Characteristics**

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient <sup>1</sup>	R <sub>0</sub> JA	61	°C/W
Thermal Resistance from Junction-to-Case <sup>1</sup>	R₀Jc	2.5	°C/W

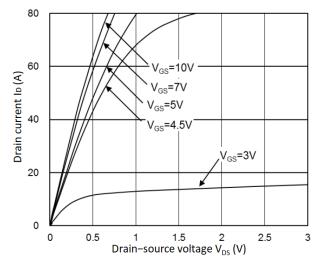


## Electrical Characteristics T<sub>c</sub> = 25°C, unless otherwise noted

Parameter		Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static Characteristics				•	•	•	
Drain-Source Breakdown Voltage		V <sub>(BR)DSS</sub>	$V_{GS} = 0V, I_D = 250\mu A$	60	-	-	V
Gate-body Leakage current		I <sub>GSS</sub>	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA
Zero Gate Voltage Drain Current	T <sub>J</sub> =25°C	- I <sub>DSS</sub>		-	-	1	- μΑ
	T <sub>J</sub> =55°C		$V_{DS} = 48V$ , $V_{GS} = 0V$	-	-	5	
Gate-Threshold Voltage		V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.2	1.9	2.5	V
Drain-Source On-Resistance <sup>2</sup>		_	V <sub>GS</sub> = 10V, I <sub>D</sub> = 10A	-	6.4	8.5	mΩ
		R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 5A	-	8.6	12	
Dynamic Characteristics	;						
Input Capacitance		Ciss	$V_{DS} = 30V, V_{GS} = 0V, f = 1MHz$	-	3307	-	pF
Output Capacitance		Coss		-	201	-	
Reverse Transfer Capacitano	e	C <sub>rss</sub>		-	151	-	
Switching Characteristic	s	1		l .		l .	
Gate Resistance		Rg	V <sub>DS</sub> = 0V, V <sub>GS</sub> =0V, f =1MHz	-	1.2	-	Ω
Total Gate Charge Qg		Qg	$V_{GS} = 10V, V_{DS} = 30V, I_{D} = 20A$	-	58	-	nC
Gate-Source Charge		Q <sub>gs</sub>		-	8.5	-	
Gate-Drain Charge	Orain Charge Q <sub>gd</sub>			-	13.8	-	
Turn-On Delay Time		t <sub>d(on)</sub>		-	16	-	
Rise Time		tr	$V_{GS} = 10V, V_{DD} = 30V$	-	41	-	
Turn-Off Delay Time		t <sub>d(off)</sub>	$R_G = 3.3\Omega$ , $I_D = 20A$	-	56.2	-	nS
Fall Time		tf		-	16	-	
Drain-Source Body Diod	e Characte	ristics					
Diode Forward Voltage <sup>2</sup> Vs		V <sub>SD</sub>	I <sub>S</sub> = 1A, V <sub>GS</sub> = 0V	-	-	1.2	V
Continuous Source Current <sup>1,5</sup>		Is	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current	-	-	75	А
Body Diode Reverse Recovery Time t <sub>rr</sub>			-	21.5	-	nS	
Body Diode Reverse Recovery Charge		Qrr	I <sub>F</sub> = 20A, dI/dt = 100A/μs	-	71	-	nC

#### Notes:

- 1. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%
- 3. The EAS data shows Max. rating . The test condition is  $V_{DD}$ =50V, $V_{GS}$ =10V,L=0.1mH, $I_{AS}$ =40A
- 4.The power dissipation is limited by 150°C junction temperature
- 5. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications , should be limited by total power dissipation.



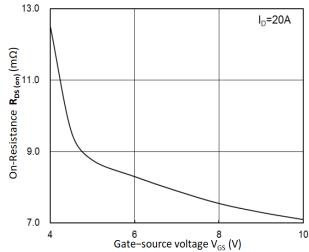
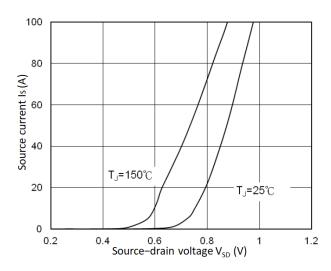


Figure 1. Typical Output Characteristics

Figure 2. R<sub>DS(on)</sub> vs. V<sub>GS</sub>



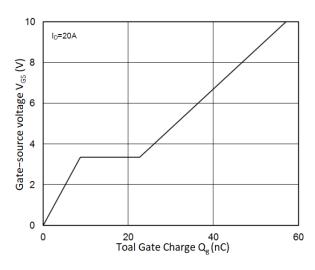
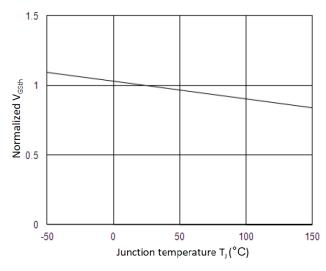


Figure 3. Forward Characteristics of Reverse

Figure 4. Gate Charge Characteristics



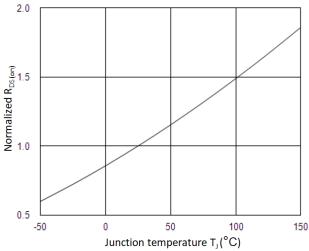


Figure 5. Normalized V<sub>GS(th)</sub> vs. T<sub>J</sub>

Figure 6. Normalized RDS(ON) vs. TJ



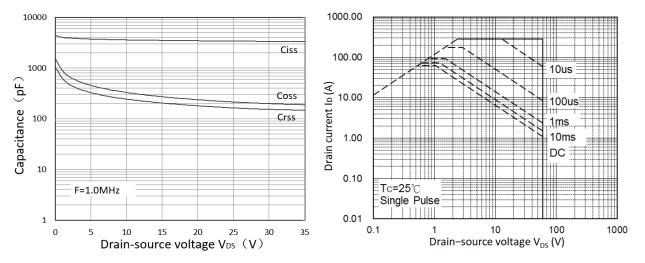


Figure 7. Capacitance Characteristics

Figure 8. Safe Operating Area

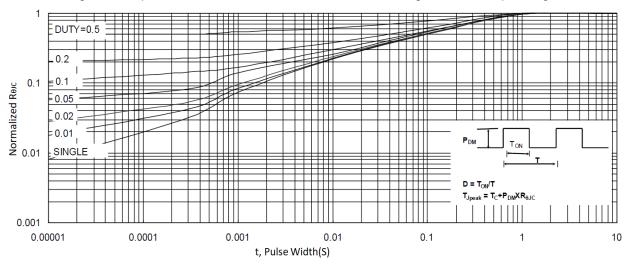


Figure 9. Normalized Maximum Transient Thermal Impedance

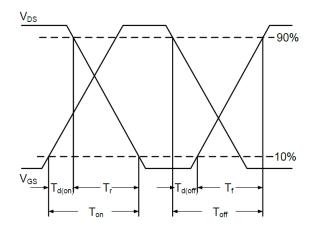


Figure 10. Switching Time Waveform

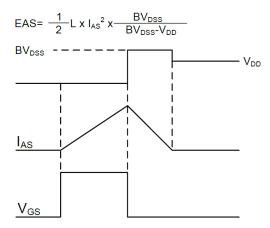
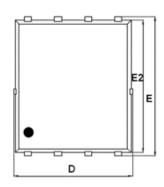


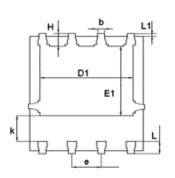
Figure 11. Unclamped Inductive Switching

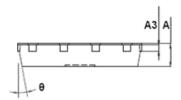
Waveform



## **Mechanical Dimensions for PDFN5060-8L**







## **COMMON DIMENSIONS**

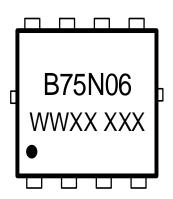
	MM			
SYMBOL	MIN	MAX		
А	0.90	1.17		
A3	0.20	0.35		
D	4.80	5.40		
E	5.90	6.15		
D1	3.61	4.31		
E1	3.3	3.78		
E2	5.65	5.85		
k	1.10	-		
b	0.30	0.51		
е	1.27BSC			
L	0.38	0.71		
L1	0.05	0.36		
Н	0.38	0.61		
θ	0°	12°		



## **Ordering Information**

Part	Part Package		Packing method	
WMB75N06T1	PDFN5060-8L	B75N06	Tape and Reel	

### **Marking Information**



B75N06 = Device code

WWXX XXX= Date code

#### **Contact Information**

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